

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ058N03LS G	**Issued**	08. April 2022
MA#	MA005710137		
Package	PG-TSDSON-8-2	**Weight***	38.22 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.076	2.82	2.82	28165	28165
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		219	
	non noble metal	iron	7439-89-6	0.168	0.44		4387	
	non noble metal	copper	7440-50-8	6.808	17.81	18.28	178117	182778
wire	non noble metal	copper	7440-50-8	0.037	0.10	0.10	966	966
encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		920	
	plastics	epoxy resin	-	1.811	4.74		47383	
	inorganic material	silicondioxide	60676-86-0	15.736	41.17	46.00	411724	460027
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10129	10129
plating	noble metal	silver	7440-22-4	0.963	2.52	2.52	25185	25185
solder	non noble metal	tin	7440-31-5	0.026	0.07		685	
	noble metal	silver	7440-22-4	0.033	0.09		856	
	non noble metal	lead	7439-92-1	1.250	3.27	3.43	32700	34241
heat sink clip	inorganic material	phosphorus	7723-14-0	0.002			49	
	non noble metal	zinc	7440-66-6	0.008	0.02		197	
	non noble metal	iron	7439-89-6	0.151	0.39		3948	
	non noble metal	copper	7440-50-8	6.127	16.03	16.44	160313	164507
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			28	
	non noble metal	zinc	7440-66-6	0.004	0.01		113	
	non noble metal	iron	7439-89-6	0.086	0.23		2256	
	non noble metal	copper	7440-50-8	3.501	9.16	9.40	91605	94002
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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